

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): A printed circuit board comprising:

a core substrate comprising a first resin substrate, a second resin substrate having an opening and a third resin substrate in a multilayer manner while interposing bonding plates, the first resin substrate including a first surface and a second surface opposite to the first surface, the opening covered with the second surface of the first resin substrate;

insulating layers and conductive circuit layers alternately laminated on the first surface of the first resin substrate;

a chip capacitor having external capacitor electrodes, the chip capacitor formed in the opening of the second resin substrate;

a first conductive pad formed on the second surface of the first resin substrate and connected to ~~an electrode~~ one of the external capacitor electrodes of the chip capacitor;

a second conductive pad formed on the second surface of the first resin substrate and connected to the other ~~electrode~~ of the external capacitor electrodes of the chip capacitor;

a first via hole formed in the first resin substrate, the first via hole directly connected to the first conductive pad and a conductive circuit on the core substrate; and

a second via hole formed in the first resin substrate, the second via hole directly connected to the second conductive pad and a conductive circuit on the core substrate.

Claim 2 (previously presented): The printed circuit board according to claim 1, wherein each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 3 (previously presented): The printed circuit board according to claim 1, wherein each of said first, second and third resin substrates having a core made of glass cloth and impregnated with a resin.

Claim 4 (currently amended): The printed circuit board according to claim 1, wherein the second resin substrate has a plurality of openings and a plurality of chip capacitors are formed in the openings.

Claim 5 (previously presented): The printed circuit board according to claim 1, wherein the conductor circuits are formed on said second resin substrate.

Claims 6-8 (canceled).

Claim 9 (currently amended): The printed circuit board according to claim 1, further comprising:

[[a]] metal ~~film~~ films formed on the ~~electrode~~ external electrodes of said chip capacitor and contacted with the first and second conductive pads, respectively.

Claim 10 (currently amended): The printed circuit board according to claim 9, wherein the metal ~~film~~ films formed on the ~~electrode~~ external electrodes of said chip capacitor ~~is-a~~ are plated ~~film~~ films comprising copper.

Claims 11-14 (canceled).

Claim 15 (currently amended): A printed circuit board constituted by alternately laminating insulating layers and conductive circuits on a core substrate containing a ~~ceramic~~ chip capacitor, which includes a first electrode, a second electrode and a dielectric made of ceramic, wherein

the core substrate containing said chip capacitor comprises a first resin substrate, a second resin substrate having an opening for containing the ~~ceramic~~ chip capacitor and a third resin substrate in a multilayer manner while interposing bonding plates,

said first resin substrate and said ~~ceramic~~ chip capacitor are coupled to each other by an insulating bonding agent and a coefficient of thermal expansion of the insulating bonding agent is lower than a coefficient of thermal expansion of said first resin substrate,

a conductive pad is formed on the first resin substrate and connected to an electrode of the chip capacitor, and

a via hole, through which the conductive pad is connected to the conductive circuit on the core substrate, is formed in the first resin substrate.

Claims 16-78 (canceled).

Claim 79 (currently amended): The printed circuit board according to claim 15, further comprising:

a metal film formed on the electrode of the chip capacitor.

Claim 80 (currently amended): The printed circuit board according to claim 79, wherein the metal film formed on the electrode of the chip capacitor is a plated film comprising copper.

Claim 81 (previously presented): The printed circuit board according to claim 15, wherein each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 82 (previously presented): The printed circuit board according to claim 15, wherein each of said first, second and third resin substrates having a core made of glass cloth and impregnated with a resin.

Claim 83 (previously presented): The printed circuit board according to claim 15, further comprising a plurality of bumps formed on an outer layer of the insulating layers and constituting a bump area,

wherein an IC chip is to be mounted on the bump area.

Claim 84 (previously presented): The printed circuit board according to claim 1, further comprising a plurality of bumps formed on an outer layer of the insulating layers and constituting a bump area, wherein at least one of the bumps is electrically connected to the electrode of the chip capacitor through a via hole formed immediately below the bump area.

Claim 85 (previously presented): The printed circuit board according to claim 84, wherein an IC chip is to be mounted on the bump area.

Claim 86 (currently amended): A printed circuit board comprising:
a core substrate comprising a first resin substrate, a second resin substrate having an opening and a third resin substrate in a multilayer manner while interposing bonding plates;
insulating layers and conductive circuit layers alternately laminated on the core substrate; and

a ceramic chip capacitor formed in the opening of the second resin substrate, the chip capacitor including a first electrode, a second electrode and a dielectric made of ceramic,

wherein each of said first, second and third resin substrates has a core made of glass cloth and impregnated with a resin.

Claim 87 (currently amended): The printed circuit board according to claim 86, further comprising:

a conductive pad formed on the first resin substrate and connected to an electrode of the chip capacitor; and

a via hole formed in the first resin substrate, the via hole directly connected to the conductive pad and the conductive circuit on the core substrate.

Claim 88 (previously presented): The printed circuit board according to claim 86, wherein each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 89 (previously presented): The printed circuit board according to claim 86, further comprising a plurality of bumps formed on an outer layer of the insulating layers and constituting a bump area, wherein at least one of the bumps is electrically connected to the electrode of the capacitor through a via hole formed immediately below the bump area.

Claim 90 (previously presented): The printed circuit board according to claim 89, wherein an IC chip is to be mounted on the bump area.

Claim 91 (new): The printed circuit board according to claim 3, wherein

the first conductive pad and the one of the external capacitor electrodes of the chip capacitor are connected via a first conductive adhesive, and

the second conductive pad and the other of the external capacitor electrodes of the chip capacitor are connected via a second conductive adhesive.

Claim 92 (new): The printed circuit board according to claim 82, wherein the conductive pad and the electrode of the chip capacitor are connected via a conductive adhesive.

Claim 93 (new): The printed circuit board according to claim 86, wherein the conductive pad and the electrode of the chip capacitor are connected via a conductive adhesive.